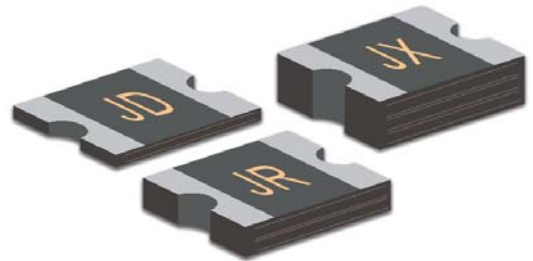
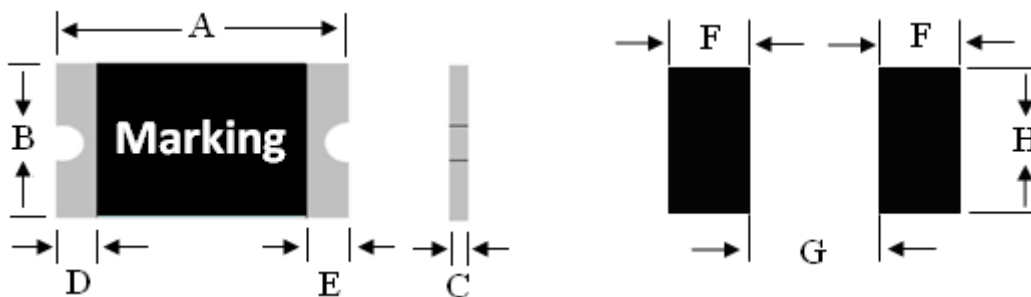


Features:

- ✧ RoHS Compliant & Halogen Free
- ✧ Faster tripping, 1210 Dimension, Surface mountable, Solid state
- ✧ Operating Current: 1.5A~7.5A
- ✧ Maximum Voltage: 6V/12V
- ✧ Operating Temperature: -40℃~85℃
- ✧ Certification: CSA



Product Dimensions (mm)



Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
SMD1210P150L	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P150L-12	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P175L	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P175L-12	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P190L	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P190L-12	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P200L	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P200L-12	3.0	3.43	2.35	2.8	0.3	0.7	0.25	0.1
SMD1210P260L	3.0	3.43	2.35	2.8	0.4	1.0	0.25	0.1
SMD1210P260L-12	3.0	3.43	2.35	2.8	0.4	1.0	0.25	0.1
SMD1210P300L	3.0	3.43	2.35	2.8	0.4	1.0	0.25	0.1

Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
SMD1210P300L-12	3.0	3.43	2.35	2.8	0.4	1.0	0.25	0.1
SMD1210P350L	3.0	3.43	2.35	2.8	0.4	1.2	0.25	0.1
SMD1210P350L-12	3.0	3.43	2.35	2.8	0.4	1.2	0.25	0.1
SMD1210P380L	3.0	3.43	2.35	2.8	0.4	1.2	0.25	0.1
SMD1210P380L-12	3.0	3.43	2.35	2.8	0.4	1.2	0.25	0.1
SMD1210P400L	3.0	3.43	2.35	2.8	0.5	1.2	0.25	0.1
SMD1210P400L-12	3.0	3.43	2.35	2.8	0.5	1.2	0.25	0.1
SMD1210P450L	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P450L-12	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P500L	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P500L-12	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P550L	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P550L-12	3.0	3.43	2.35	2.8	0.5	1.4	0.25	0.1
SMD1210P600L	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P600L-12	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P650L	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P650L-12	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P700L	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P700L-12	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P750L	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1
SMD1210P750L-12	3.0	3.43	2.35	2.8	0.5	1.6	0.25	0.1

Recommended Solder Pad Layout Dimensions (mm)

Device	F	G	H
	Normal Value	Normal Value	Normal Value
1210 Series	1.0	2.0	2.5

Electrical Characteristics

Model	V _{MAX} (V)	I _{MAX} (A)	I _H (A)	I _T (A)	P _D (W)	Maximum Time-to-Trip		Resistance	
						Current	Time	R _{iMIN}	R _{1MAX}
						(A)	(Sec)	(Ω)	(Ω)
SMD1210P150L	6.0	50.0	1.5	3.0	0.8	8.0	2.0	0.010	0.060
SMD1210P150L-12	12.0	50.0	1.5	3.0	0.8	8.0	2.0	0.010	0.060
SMD1210P175L	6.0	50.0	1.75	3.5	0.8	8.0	2.0	0.005	0.040

SMD1210P175L-12	12.0	50.0	1.75	3.5	0.8	8.0	2.0	0.005	0.040
SMD1210P190L	6.0	50.0	1.9	3.8	0.8	8.0	3.0	0.006	0.037
SMD1210P190L-12	12.0	50.0	1.9	3.8	0.8	8.0	3.0	0.006	0.037
SMD1210P200L	6.0	50.0	2.0	4.0	0.8	8.0	3.0	0.006	0.035
SMD1210P200L-12	12.0	50.0	2.0	4.0	0.8	8.0	3.0	0.006	0.035
SMD1210P260L	6.0	50.0	2.6	5.2	0.8	13.0	2.0	0.003	0.025
SMD1210P260L-12	12.0	50.0	2.6	5.2	0.8	13.0	2.0	0.003	0.025
SMD1210P300L	6.0	50.0	3.0	6.0	0.8	15.0	2.0	0.003	0.02
SMD1210P300L-12	12.0	50.0	3.0	6.0	0.8	15.0	2.0	0.003	0.02
SMD1210P350L	6.0	50.0	3.5	7.0	0.8	17.5	2.0	0.002	0.018
SMD1210P350L-12	12.0	50.0	3.5	7.0	0.8	17.5	2.0	0.002	0.018
SMD1210P380L	6.0	50.0	3.8	7.6	0.8	19.0	2.0	0.002	0.016
SMD1210P380L-12	12.0	50.0	3.8	7.6	0.8	19.0	2.0	0.002	0.016
SMD1210P400L	6.0	50.0	4.0	8.0	0.8	20.0	2.0	0.002	0.014
SMD1210P400L-12	12.0	50.0	4.0	8.0	0.8	20.0	2.0	0.002	0.014
SMD1210P450L	6.0	50.0	4.5	9.0	1.0	22.5	2.0	0.001	0.013
SMD1210P450L-12	12.0	50.0	4.5	9.0	1.0	22.5	2.0	0.001	0.013
SMD1210P500L	6.0	50.0	5.0	10.0	1.0	25.0	2.0	0.001	0.012
SMD1210P500L-12	12.0	50.0	5.0	10.0	1.0	25.0	2.0	0.001	0.012
SMD1210P550L	6.0	50.0	5.5	11.0	1.0	27.5	2.0	0.001	0.011
SMD1210P550L-12	12.0	50.0	5.5	11.0	1.0	27.5	2.0	0.001	0.011
SMD1210P600L	6.0	50.0	6.0	12.0	1.2	30.0	2.0	0.001	0.010
SMD1210P600L-12	12.0	50.0	6.0	12.0	1.2	30.0	2.0	0.001	0.010
SMD1210P650L	6.0	50.0	6.5	13.0	1.2	32.5	2.0	0.001	0.009
SMD1210P650L-12	12.0	50.0	6.5	13.0	1.2	32.5	2.0	0.001	0.009
SMD1210P700L	6.0	50.0	7.0	14.0	1.2	35.0	2.0	0.001	0.008
SMD1210P700L-12	12.0	50.0	7.0	14.0	1.2	35.0	2.0	0.001	0.008
SMD1210P750L	6.0	50.0	7.5	15.0	1.2	37.5	2.0	0.001	0.007
SMD1210P750L-12	12.0	50.0	7.5	15.0	1.2	37.5	2.0	0.001	0.007

Thermal Derating Chart-I_H(A)

Model	Maximum ambient operating temperature (°C)								
	-40	-20	0	25	40	50	60	70	85
SMD1210P150L	2.25	2.00	1.75	1.50	1.33	1.15	1.05	0.93	0.70
SMD1210P150L-12	2.25	2.00	1.75	1.50	1.33	1.15	1.05	0.93	0.70
SMD1210P175L	2.55	2.33	2.02	1.75	1.53	1.35	1.23	1.07	0.85
SMD1210P175L-12	2.55	2.33	2.02	1.75	1.53	1.35	1.23	1.07	0.85

SMD1210P190L	2.81	2.53	2.20	1.90	1.67	1.47	1.34	1.17	0.91
SMD1210P190L-12	2.81	2.53	2.20	1.90	1.67	1.47	1.34	1.17	0.91
SMD1210P200L	2.96	2.67	2.32	2.00	1.76	1.55	1.41	1.23	0.96
SMD1210P200L-12	2.96	2.67	2.32	2.00	1.76	1.55	1.41	1.23	0.96
SMD1210P260L	3.85	3.47	3.02	2.60	2.29	2.01	1.84	1.59	1.25
SMD1210P260L-12	3.85	3.47	3.02	2.60	2.29	2.01	1.84	1.59	1.25
SMD1210P300L	4.40	3.98	3.45	3.00	2.64	2.30	2.15	1.83	1.42
SMD1210P300L-12	4.40	3.98	3.45	3.00	2.64	2.30	2.15	1.83	1.42
SMD1210P350L	5.18	4.67	4.06	3.50	3.08	2.71	2.47	2.15	1.68
SMD1210P350L-12	5.18	4.67	4.06	3.50	3.08	2.71	2.47	2.15	1.68
SMD1210P380L	5.55	5.02	4.35	3.80	3.32	2.92	2.65	2.30	1.81
SMD1210P380L-12	5.55	5.02	4.35	3.80	3.32	2.92	2.65	2.30	1.81
SMD1210P400L	5.92	5.33	4.64	4.00	3.52	3.09	2.83	2.45	1.92
SMD1210P400L-12	5.92	5.33	4.64	4.00	3.52	3.09	2.83	2.45	1.92
SMD1210P450L	6.12	5.39	5.16	4.50	3.85	3.35	3.00	2.36	1.56
SMD1210P450L-12	6.12	5.39	5.16	4.50	3.85	3.35	3.00	2.36	1.56
SMD1210P500L	7.40	6.67	5.80	5.00	4.40	3.87	3.53	3.07	2.40
SMD1210P500L-12	7.40	6.67	5.80	5.00	4.40	3.87	3.53	3.07	2.40
SMD1210P550L	8.14	7.34	6.38	5.50	4.84	4.26	3.88	3.38	2.64
SMD1210P550L-12	8.14	7.34	6.38	5.50	4.84	4.26	3.88	3.38	2.64
SMD1210P600L	8.65	7.91	6.93	6.00	5.23	4.45	4.00	3.63	2.85
SMD1210P600L-12	8.65	7.91	6.93	6.00	5.23	4.45	4.00	3.63	2.85
SMD1210P650L	9.20	8.45	7.45	6.50	5.60	4.65	4.30	3.89	3.00
SMD1210P650L-12	9.20	8.45	7.45	6.50	5.60	4.65	4.30	3.89	3.00
SMD1210P700L	9.84	9.00	7.95	7.00	5.96	4.95	4.50	4.16	3.20
SMD1210P700L-12	9.84	9.00	7.95	7.00	5.96	4.95	4.50	4.16	3.20
SMD1210P750L	10.5	9.65	8.50	7.50	6.40	5.30	4.80	4.45	4.42
SMD1210P750L-12	10.5	9.65	8.50	7.50	6.40	5.30	4.80	4.45	4.42

Test Procedures and Requirements

Test Item	Test Conditions	Accept/Reject Criteria
Initial Resistance	In still air at 25°C	$R_{iMIN} \leq R \leq R_{iMAX}$
Time to Trip	Specified current, V_{MAX} , 25°C	$T \leq$ Maximum Time to Trip
Holding Current	30min, at I_H , 25°C	No trip
Trip Cycle Life	V_{MAX} , I_{MAX} , 100 cycles	No arcing or burning
Trip Endurance	V_{MAX} , I_{MAX} , 1 hour	No arcing or burning

Physical Characteristics

Terminal Materials	Tin-Plated Nickle-copper
Soldering Zone	Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.
Moisture Sensitivity	Level 2a, per IPC/JEDEC J-STD 020C

Environmental Specifications

Test Item	Test Conditions	Resistance Change
Passive Aging	85°C, 1000 hours	±10% typical
Humidity Aging	85°C/85%RH, 100 hours	±5% typical
Thermal Shock	MIL-STD-202, Method 107G +85°C/-40°C, 20 times	-30% typical
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	ML-STD-883C, Test Condition A	No change

Electrical Specifications

I_H =Hold current: Maximum current at which the device will not interrupt in 25°C still air.

I_T =Trip current: Minimum current at which the device from low resistance to high resistance in 25°C still air.

V_{MAX} =Maximum continuous voltage device can withstand without damage at rated current.

I_{MAX} =Maximum fault current device can withstand without damage at rated voltage.

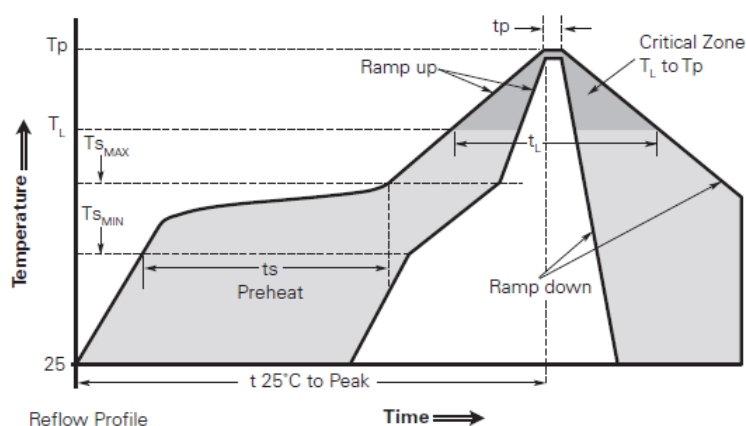
Maximum Time-to-trip: Maximum time to trip at assigned current.

P_D =Typical power dissipation: Typical amount of power dissipated from the device when in 25°C still air environment.

R_{iMIN} =Minimum resistance of device at 25°C prior to tripping.

$R1_{MAX}$ = Maximum device resistance is measured one hour post reflow.

Solder Reflow Profiles



Profile Feature	Pb-Free Assembly
Average ramp up rate(T_{sMAX} to T_p)	3°C/second max.
Preheat	
• Temperature min. (T_{sMIN})	150°C
• Temperature max. (T_{sMAX})	200°C
• Time (T_{sMIN} to T_{sMAX})	60-120 seconds
Time maintained above:	
• Temperature (T_L)	217°C
• Time (T_L)	60-150 seconds
Peak/Classification temperature (T_p)	260°C
Time within 5°C of actual peak temperature	
Time (T_p)	30 seconds max.
Ramp down rate	3°C/second max.
Time 25°C to peak temperature	8 minutes max.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.

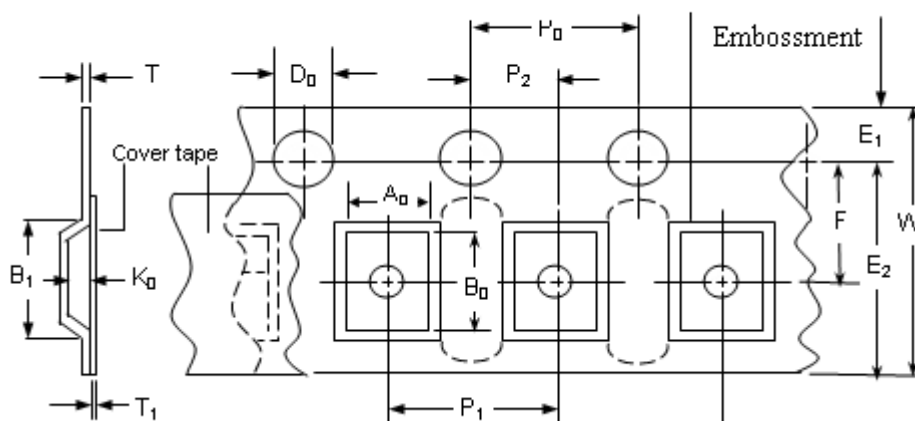
Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperature exceed the recommended profile, devices may not meet the performance requirements.

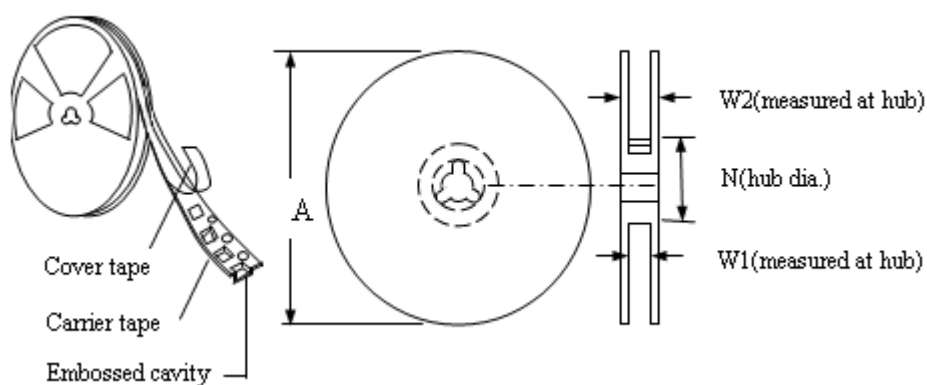
Tape Specifications and Reel Dimensions

Covering Specifications EIA 481-1	
W	8.0 ± 0.3
P ₀	4.0 ± 0.10
P ₁	4.0 ± 0.10
P ₂	2.0 ± 0.05
A ₀	2.82 ± 0.10
B ₀	3.46 ± 0.10
D ₀	1.55 ± 0.05
F	3.50 ± 0.05
E ₁	1.75 ± 0.10
T	0.25 ± 0.10
Leader min.	390
Trailer min.	160
Reel Dimensions	
A	178 ± 1.0
N	59 ± 1
W ₁	$8.5 \pm 1.0 / -0.2$
W ₂	12.0 ± 1

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage

The maximum ambient temperature shall not exceed 40°C. Storage temperatures higher than 40°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use, the products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Please read this specification before using the product.
- Use PPTC beyond the maximum ratings or improper use may result in device damage, electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.